

The Eighth International Conference on Fundamentals of Fracture (ICFF VIII)

3 - 7 January 2008, Hong Kong & Guangzhou

First Call for Papers



The Eighth International Conference on Fundamentals of Fracture (ICFF VIII) is the successor of the previous seven held at NBS, Gaithersburg (USA, 1983), Gatlinburg (USA, 1985), Irsee (Germany, 1989), Urabandai (Japan, 1993), NIST, Gaithersburg (USA, 1997), Cirencester (UK, 2001), and Nancy (France, 2005). You are warmly invited to participate in ICFF VIII which will be held 3-7 January 2008 in Hong Kong University of Science and Technology, Hong Kong, and in Guangzhou, China. As the previous conferences, ICFF VIII provides an international forum for presentation and discussion of the latest scientific and technological development in fundamentals of fracture. The general theme of ICFF VIII is to cover all aspects of fracture at a fundamental level, including contributions from those working in the disciplines of Continuum Mechanics, Physics, Chemistry, Bioscience, Metallurgy, Ceramics, Polymer Science, etc. You are cordially invited to submit an abstract to join in this memorable event.

Major topics of ICFF VIII include theory, modelling, calculations, simulations, and experiments in,

- *Fracture, creep, and fatigue at the atomistic, mesoscopic, and macroscopic scales,*
- *Fracture, creep, and fatigue of engineering materials,*

- *Fracture, creep, and fatigue of smart materials,*
- *Fracture, creep, and fatigue of biomaterial,*
- *Environment effects,*
- *Fracture, creep, and fatigue under mechanical, thermal, electrical, and/or magnetic loading,*
- *Reliability and failure analysis of electronic devices and electronic packaging,*
- *Dynamic fracture.*

In order to enhance the interactivity between the participants, the number of delegates will be limited. The scientific exchanges will be achieved through keynote presentations from leading researchers and poster sessions. Excellent posters will be recognized by Poster Awards.

Abstracts and Papers

An electronic form (MS-Word format) of two-page extended abstract with name, address, phone/fax numbers, and e-mail address should be submitted to the Secretariat of ICFF VIII, icff8@ust.hk by **August 31, 2007**. Accepted abstracts will be published in an abstract booklet. All delegates are encouraged to submit full manuscripts for publication in special issues of international journals. Instructions for full paper submission will be sent to the authors whose abstracts are accepted after review. The details of further information including registration and accommodation will be announced later through Email and the ICFF VIII website.



Important Dates

- Aug. 31, 2007 Extended abstract submission
- Sep. 30, 2007 Abstract acceptance
- Nov. 30, 2007 Full manuscript due
- Nov. 30, 2007 Registration/hotel accommodation

Registration Fee

Including refreshment, lunch, reception, banquet, transportation from hotels to HKUST and from Hong Kong to Guangzhou

US\$400 (or HK\$3,200) before Nov. 30, 2007

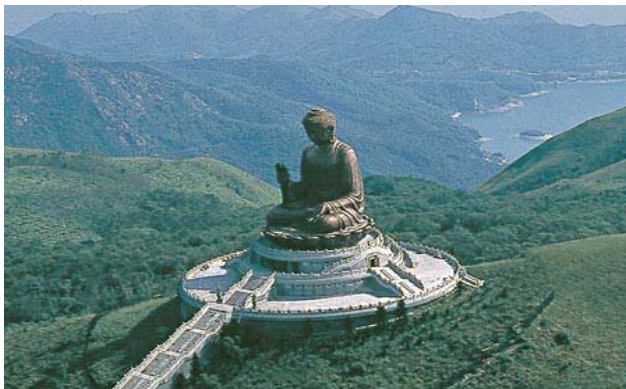
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